



REV	MODIFICATION	DATE	DRAW
A0	Release To ECN20150703	2015.07.15	Michelle
A1	Release To ECN20150808	2015.08.24	Michelle

Specification

- 1.Current Rating:3A AC/DC
- 2.Voltage Rating:250V AC/DC
- 3.Contact Resistance:20mΩ Max.
- 4.Insulation Resistance:1000MΩ Min. At DC 500V
- 5.Dielectric Withstanding Voltage:AC1000V/Minute
- 6.Operating Temperature:-25°C~+85°C

RoHS Compliant

Material:

- 1.Housing:High Temperature Thermoplastic UL94V-2
- 2.Contact Pin:Copper Alloy SQ. Pin 0.64mm

Finish:

- 1.Housing:Natural

- 2.Contact Pin:See P/N Option

Part No.:AD03600 XX 1 X 5 2

No. Of Pin
02~20

Packing
5:Bag

Housing Material

- 1:Nylon66 UL94V-2 Natural

Plating

- 1:Bright Tin Plated Over Nickel
- 2:Matte Tin Plated Over Nickel
- 3:Gold Plated Over Nickel

PIN	DIM.A	DIM.B	PIN	DIM.A	DIM.B	PIN	DIM.A	DIM.B	PIN	DIM.A	DIM.B
02	2.54	5.12	07	15.24	17.94	12	27.94	30.68	17	40.64	43.30
03	5.08	7.66	08	17.78	20.48	13	30.48	33.10	18	43.18	45.90
04	7.62	10.20	09	20.32	23.02	14	33.02	35.80	19	45.72	48.56
05	10.16	12.74	10	22.86	25.58	15	35.56	38.34	20	48.26	50.80
06	12.70	15.30	11	25.40	28.12	16	38.10	40.94			



金上達科技股份有限公司

GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.	TITLE: Wire To Board Wafer 2.54mm 180° DIP Single Row			
.x± 0.35	.x'± 2'	APR. C.F.Liao 20150824	PART NO. AD03600XX1X52		DWG NO. AD03600XX1X52	
.xx± 0.25	.x'± 1'	CHK. Abel 20150824	UNITS: mm	CUSTOMER DRAWING		
.xxx± 0.15	.xx'± 0.5'	DRA. Michelle 20150824	SIZE: A4	SCALE 4:1	SHEET 1 / 1	
				REV A1	V	